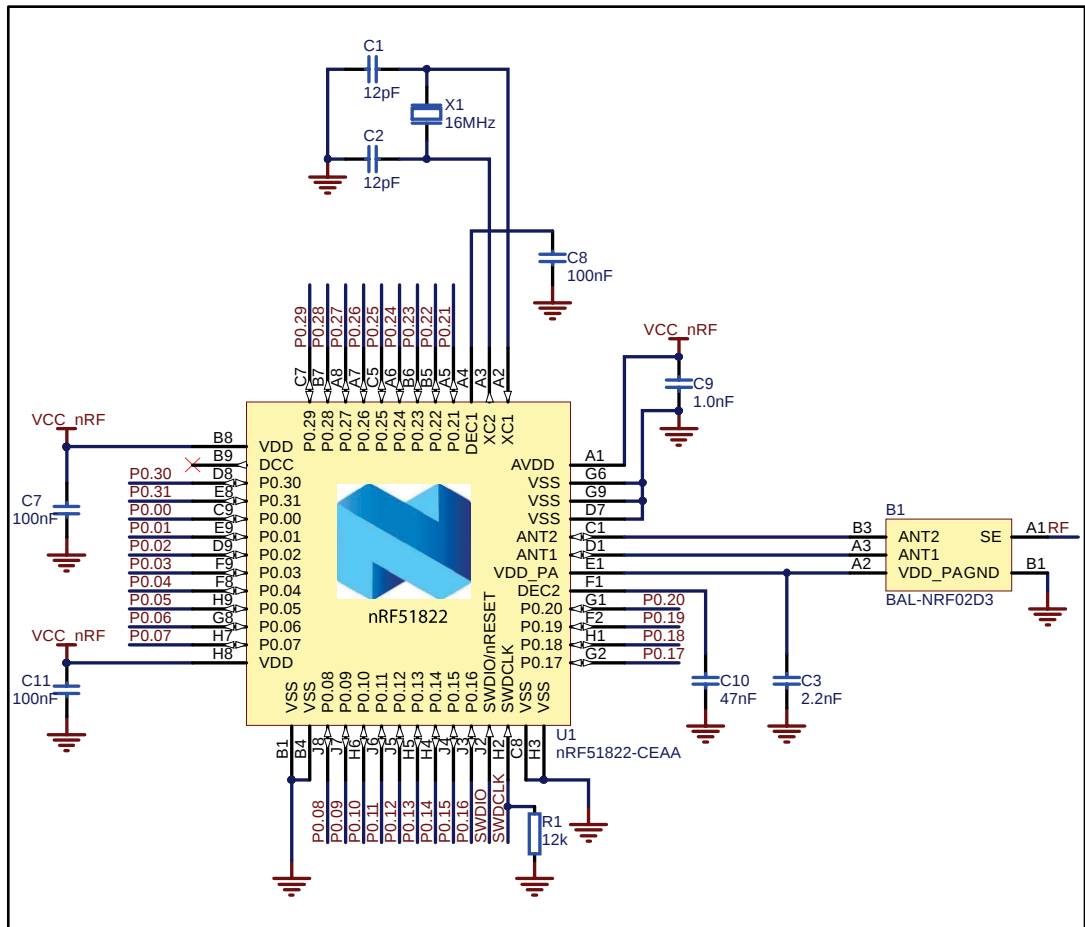


Application

Figure 2: Application schematic



1 Characteristics

Table 1: Absolute ratings (limiting values)

Symbol	Parameter	Value			Unit
		Min.	Typ.	Max.	
P _{IN}	Input power R _{FIN}		-	20	dBm
V _{ESD}	ESD ratings human body model (JESD22-A114-C), all I/O one at a time while others connected to GND	2000	-		V
	ESD ratings charge device model (JESD22-C101-C)	500	-		
	ESD ratings machine model, all I/O	200	-		
T _{OP}	Operating temperature (JESD22-A115-C), all I/O	-40	-	+105	°C
T _{stg}	Storage temperature range	-55°C		+150	°C

Table 2: Impedances (T_{amb} = 25 °C)

Symbol	Parameter	Value			Unit
		Min.	Typ.	Max.	
Z _{OUT}	Nominal differential output impedance	-	matched	-	Ω
Z _{IN}	Nominal input impedance	-	50	-	Ω

Table 3: RF performances (T_{amb} = 25 °C)

Symbol	Parameter		Value			Unit
			Min.	Typ.	Max.	
f	Frequency range (bandwidth)		2400		2540	MHz
I _L	Insertion loss in bandwidth			1.9		dB
RL	Return loss in bandwidth			12		dB
φ _{imb}	Phase imbalance			6		°
A _{imb}	Amplitude imbalance			0.15		dB
2f ₀	2nd harmonic S ₂₁ attenuation	4880 MHz	44	10		dB
3f ₀	3rd harmonic S ₂₁ attenuation	7320 MHz		20		dB

1.1 On-board measurements

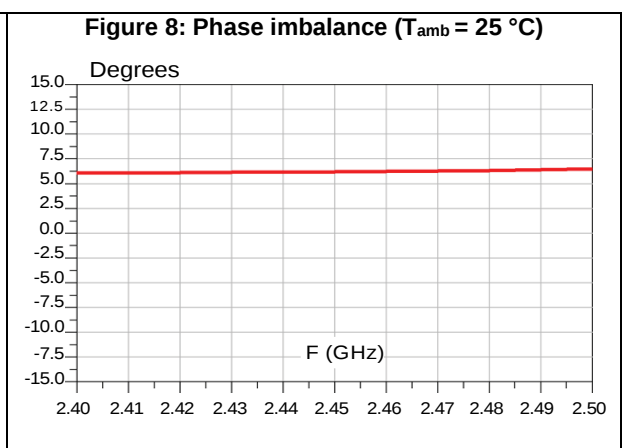
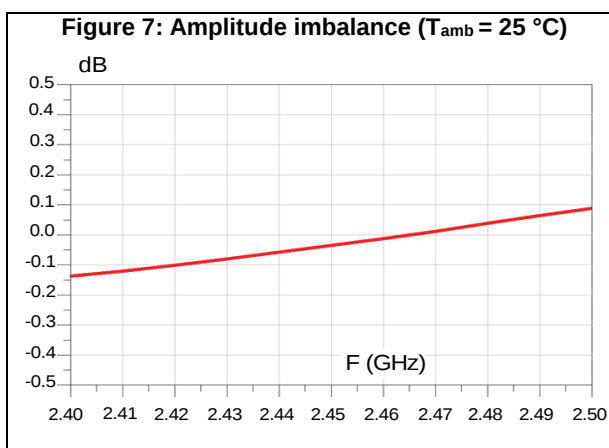
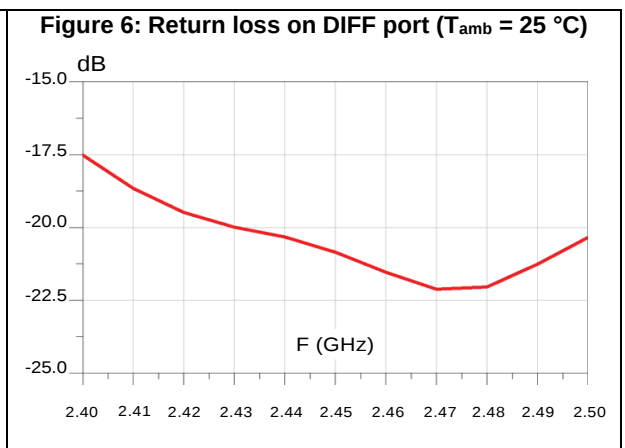
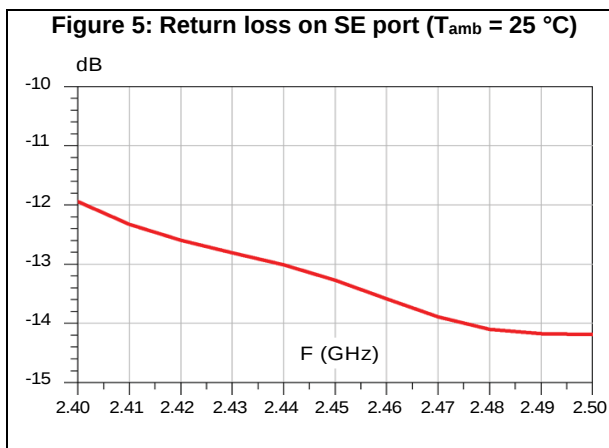
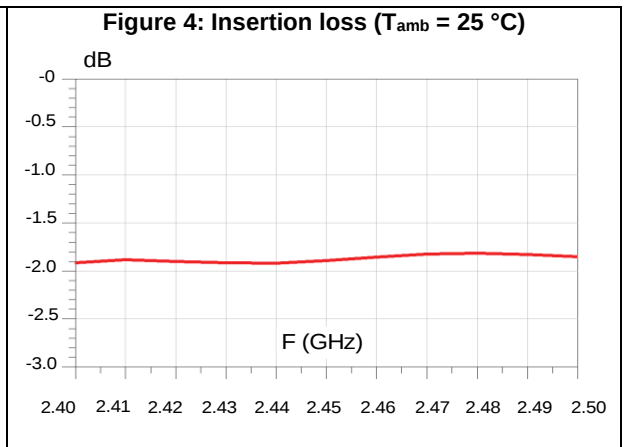
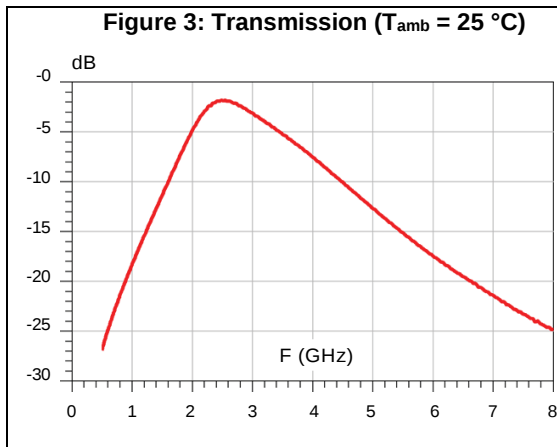


Table 4: Compatibility matrix (nRF51422)

nRF51422 IC revision	Packet/variant	Build code
1	CEAA	A0A
2	CEAA	Bx0
3	CDAB	Ax0
	CEAA	Cx0
	CFAC	Ax0

Table 5: Compatibility matrix (nRF51822)

nRF51822 IC revision	Packet/variant	Build code
1	CEAA	BA
	CEAA	B0
2	CEAA	CA0
	CEAA	DA0
	CEAA	Dx0
3	CDAB	Ax0
	CEAA	Ex0
	CFAC	Ax0

2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

- Epoxy meets UL94, V0
- Lead-free package

2.1 Flip-Chip 5 bumps package information

Figure 9: Flip-Chip 5 bumps package outline

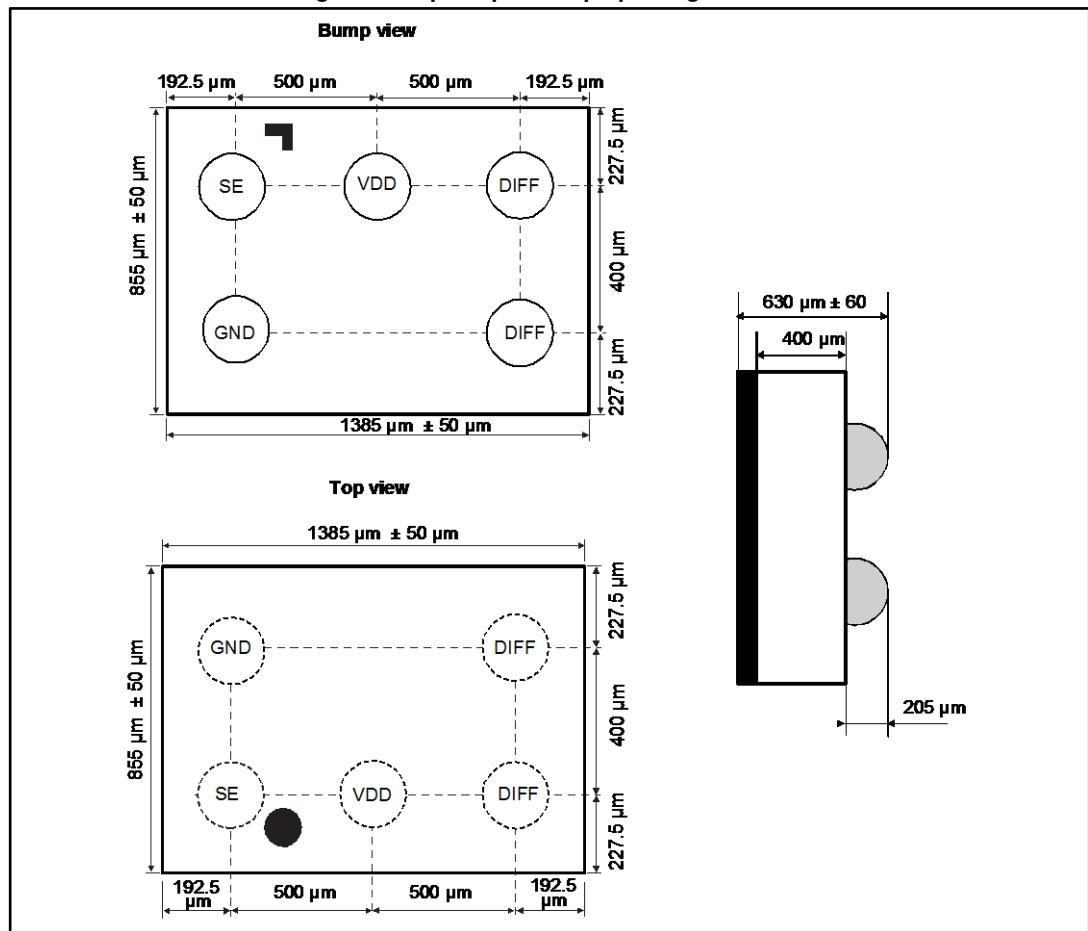


Figure 10: Recommended land pattern

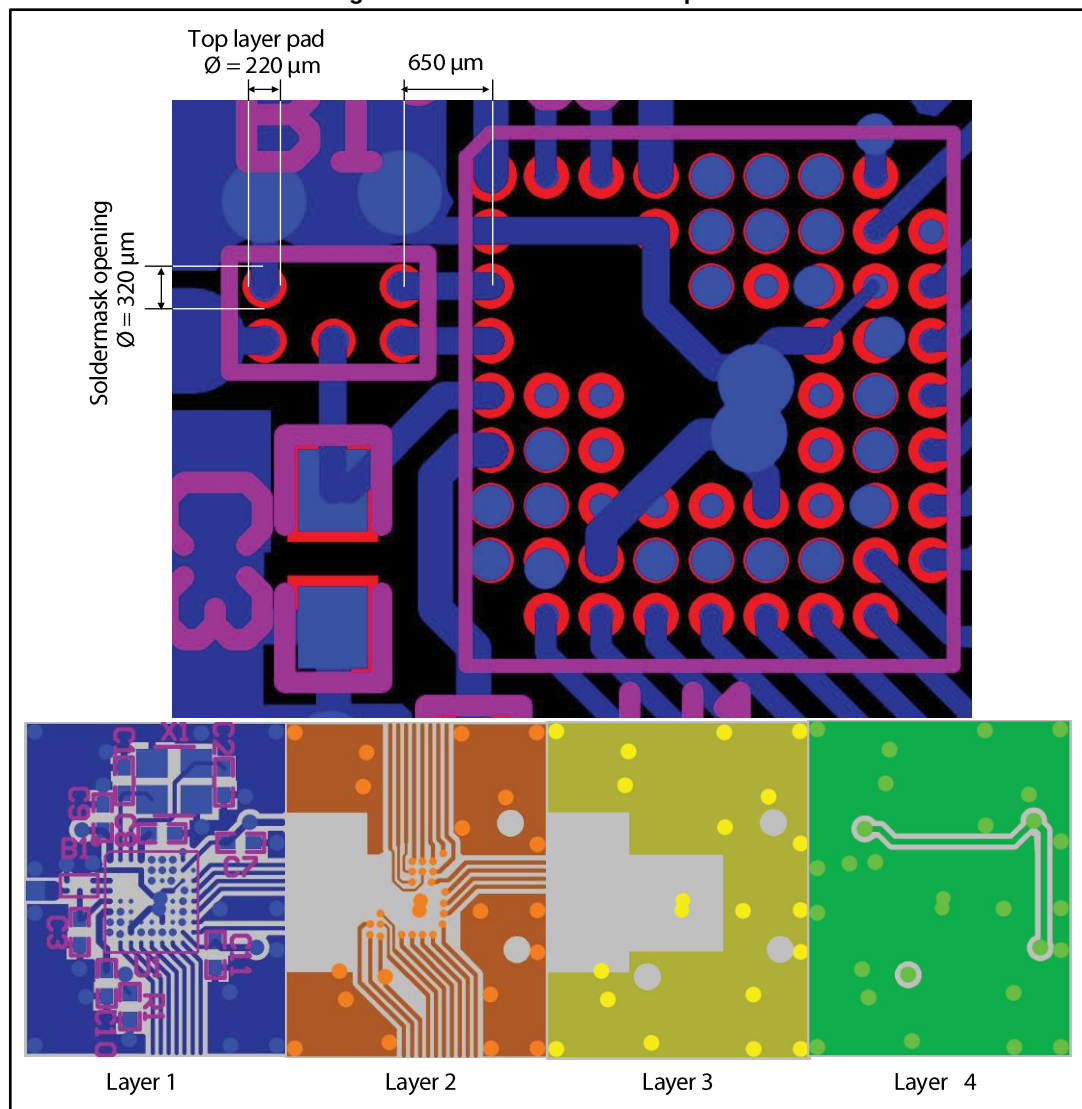
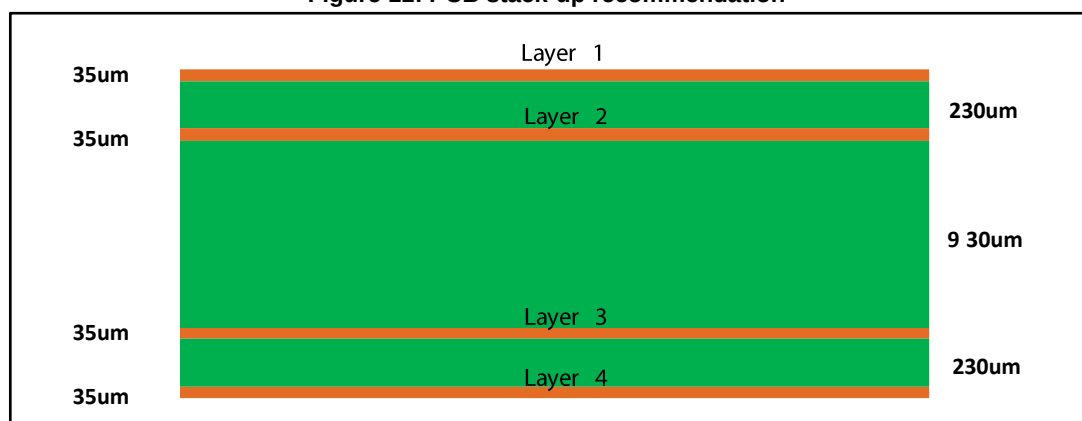


Figure 11: PCB stack-up recommendation



2.2 Flip-chip 5 bumps packing information

Figure 12: Marking

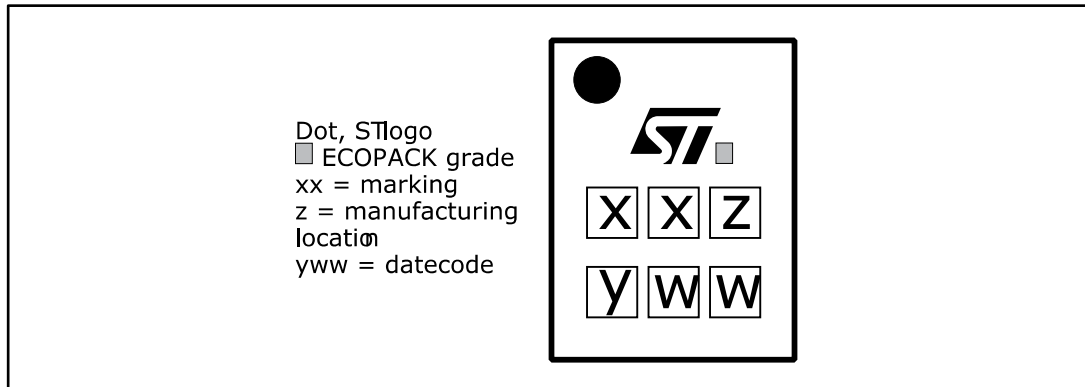
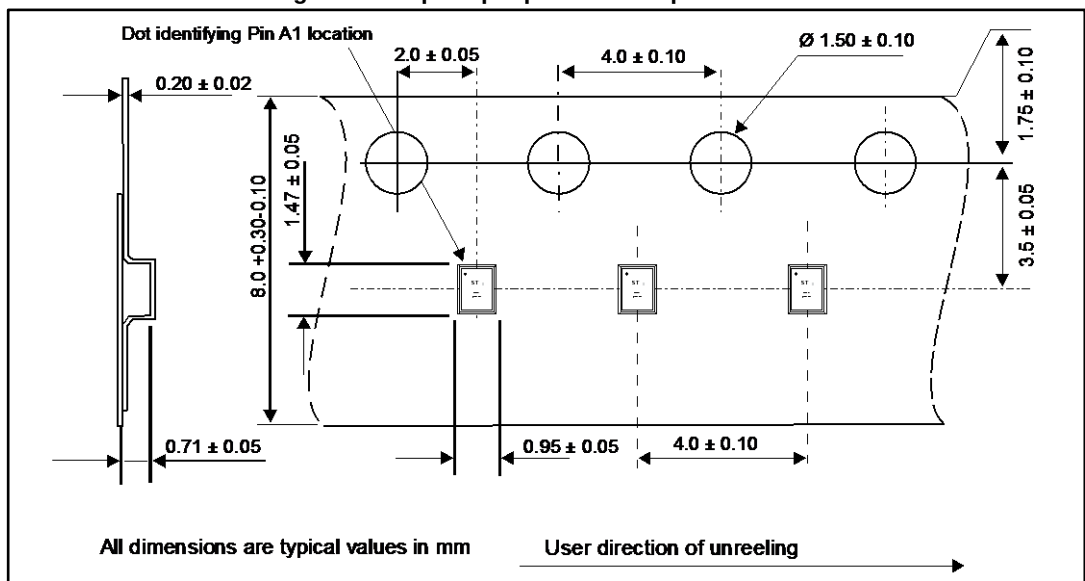


Figure 13: Flip Chip tape and reel specifications



More packing information is available in the application note:

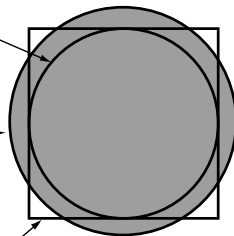
- AN2348 Flip-Chip: "Package description and recommendations for use"
- AN4315: "BAL-NRF02D3 matched balun with integrated harmonics filter for Nordic Semiconductor ultralow power transceivers"

Figure 14: Footprint - 3 mils stencil -non solder mask defined

Copper pad diameter:
220 μm recommended
180 μm minimum
260 μm maximum

Solder mask opening:
320 μm recommended
300 μm minimum
340 μm maximum

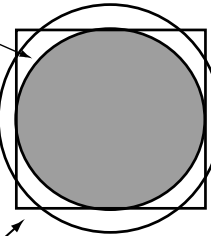
Solder stencil opening:
220 μm recommended

**Figure 15: Footprint - 3 mils stencil - solder mask defined**

Solder mask opening:
220 μm recommended
180 μm minimum
260 μm maximum

Copper pad diameter:
320 μm recommended
300 μm minimum

Solder stencil opening:
220 μm recommended

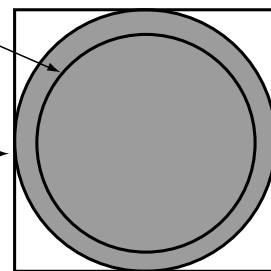
**Figure 16: Footprint - 5 mils stencil -non solder mask defined**

Copper pad diameter:
220 μm recommended
180 μm minimum
260 μm maximum

Solder mask opening:
320 μm recommended
300 μm minimum
340 μm maximum

Solder stencil opening:
330 μm recommended*

*depending on paste, it can go down to 270 μm

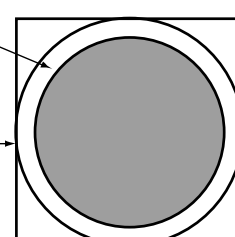
**Figure 17: Footprint - 5 mils stencil - solder mask defined**

Solder mask opening:
220 μm recommended
180 μm minimum
260 μm maximum

Copper pad diameter:
320 μm recommended
300 μm minimum

Solder stencil opening:
330 μm recommended*

*depending on paste, it can go down to 270 μm



3 Ordering information

Table 6: Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
BAL-NRF02D3	SK	Flip-Chip 5 bumps	1.44 mg	5000	Tape and reel

4 Revision history

Table 7: Document revision history

Date	Revision	Changes
02-Jul-2013	1	Initial release.
30-Aug-2013	2	Updated <i>Table 1</i> .
13-Oct-2014	3	Updated <i>Figure 9</i> .
25-Mar-2015	4	Updated cover page, added <i>Table 4</i> and <i>Table 5</i> .
15-Jun-2015	5	Updated <i>Table 1</i> .
07-Dec-2016	6	Updated <i>Table 1</i> : "Absolute ratings (limiting values)".
02-Aug-2017	7	Updated Section 3: "Ordering information".
14-Nov-2017	8	Updated Section "Benefits" .

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